Texas Instruments Inc. Search results for "TL3472CD"

TI Part Number TI, 347 2CD Assembly Site TI ASULASCAL INTES Dead/Ball Finish Cold NIFCAU Package Dedy Size (WsLAH) mm 3/14.40.158 Planned Lead/Pall Finish Cold Part Part Part Part Part Part Part Part	Current Production Informatio	n							
Plannet Lead/Ball Finish Package Body Size (WkL4H) cm 3 21X 4931 SB RNS. / Reflow Stations Verol 1-260C-Ukl IX Total Dovice Mass (son) 7.2 0.19931 Environmental Ratings Information Sid JIG Material Content Compliant I Verol 1-260C-Ukl IX	TI Part Number		TL3472CD	TL3472CD		Assembly Site		TI AGUASCALIENTES	
MSL Reflow Ratings Level 1.260C-UNLIM Total Device Mass (mg) 72.419993 Part Number Type Std JIS Material Content Compliant (evel A & B. Part Reflow Frage Compliant Y Green Compliant (a) (b) Partee (Refl-S) Conversion Date D1 Aug.2003 (DC 0331) Green Conversion Date D1 Aug.2003 (DC 0331) Green Conversion Date D1 Aug.2003 (DC 0331) Partee (Refl-S) Conversion Date D1 Aug.2003 (DC 0331) Green Conversion Date D1 Aug.2003 (DC 0331) Green Conversion Date D1 Aug.2003 (DC 0331) Component Local Stda 74.40-75.5 0.109989 99.973 99972 0.1518 Bond Wre Material Stiver 74.40-77.2 0.000001 0.0000 0	Lead/Ball Finish		CU NIPDAU	CU NIPDAU		Package Type / Pins		D 8	
Environmental Ratings Information Use of a large program of the set of								3.91x4.9x1.58	
Part Number Type Isid JI G Material Content Compliance Level A & B. Both S A High Temp Compliant Y Green Compliant Y PB-Free (RoHS) Conversion Date 01-Jul 2005 (DC 057) Green Conversion Date 01-Jul 2005 (DC 057) PB-Free (RoHS) Variable Supply Date 15-Agr-2005 Green Conversion Date 01-Jul 2005 (DC 057) Component Information Advance Percentage % ppn Percentage % ppn Component Level Congeneous Material Level Component Level Percentage % ppn Percentage % ppn Metallaruty Cold 7440-57-5 0.19990 0.0000 0.0015 0.0000 0.0012 0.0000 0.0012 0.0000 0.0012 0.0000 0.0012 0.0000 0.0012 0.0000 0.0012 0.0001 0.	MSL / Reflow Ratings		Level-1-260C-UNLI	Level-1-260C-UNLIM				72.619993	
RoHS Y Green Compilant Y Y Pb-Free (RoHS) Available Supply Date 15.4gr-2003 (CC 037) Green Conversion Date 17-1JL-2005 (CC 0527) 17-1JL-2005 (CC 0527) Pb-Free (RoHS) Available Supply Date 15.4gr-2003 (CC 037) Green Available Supply Date 17-1JL-2005 (CC 0527) 17-1JL-2005 (CC 0527) Component Information Subtance CAS Number Parce (RoHS) Parce RoHS) Parce RoHS Parce RoHS Parce RoHS) Parce RoHS Parce	Environmental Ratings Informa	ation							
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Component Substance CAS Number Amount (ng) Homogenous Material Level Component Level Bond Wire	Pb-Free (RoHS) Conversion Date		01-Aug-2003 (DC 0331)		Green Conversion Date		01-Jul-2005 (DC 0527)		
Companent Substance CAS Number Homogeneous Material Level Component Level Component Level Percentage % ppr Read Wire Interaction of the second			15-Apr-2005		Green Available Supply Date		15-Mar-2006		
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Component Substance CAS Number Parcentage % ppr Percentage % ppr Bend Wire Metallurgy Gold 7440-57.5 0.109989 99.9973 999972 0.1515 Trace Metal Beryllium 7440-71.7 0.000001 0.0009 9 0 Trace Metal Calcium 7440-72.2 0.000001 0.0009 9 0 Sub-Total Image Metal Silver 7440-22.4 0.019992 100 100000 0.1515 Die Attach Adhesive Image Metal Silver 0.019992 100 100000 0.0218 Polymer Proprietary Resin 7440-22.4 0.0158 79 790000 0.0218 Polymer Proprietary Resin 0.002 13 130000 0.0038 Sub-Total Proprietary Metrial 0.002 100 1000000 0.0275 East Metal Copper 7440-50-8 24.025981 97.425 3.0845 Base Metal Iron 7439-92-1 </td <td></td> <td></td> <td></td> <td></td> <td colspan="2">Homogeneous Material Level</td> <td colspan="2">Component Level</td>					Homogeneous Material Level		Component Level		
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Sub-Total 0.0039 100 0.00537 Mold Compound	Plating	Palladium	7440-05-3	0.001599	9 4.1	41000	0.0022	22	
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				47.5	5 100			654087	
	Semiconductor Device						•		
Silicon Chip Doped Silicon 7440-21-3 0.29 100 100000 0.3993		Doped Silicon	7440-21-3	0.29	9 100	1000000	0.3993	3993	
Sub-Total 0.29 100 100000 0.3993								3993	
Total 72.619993 100				72 610003				1000000	

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, SeeProduct Content Methodology,

Material Declaration Certificate for Semiconductor Products

TI certifies that the material content information provided by TI as of the date of disclosure is representative and accurate. TI semiconductor products designated by TI as "Pb-Free" or "Green" (defined below) do not exceed any of the Joint Industry Guide (JIG) Level-A Substance thresholds and are compliant with the requirements of the European Union's Restriction on Use of Hazardous Substances ("RoHS") Directive, 2002/95/EC.

For TI semiconductor products NOT designated as "Pb-Free" or "Green", these products are RoHS compliant with the exception of Lead (Pb) which may be found in the leadframe plating or solder balls, or in RoHS exempt applications such as high-temperature solder die attach (exemption 7a) and flip-chip solder bumps (exemption 15). This situation is known as RoHS-5 or "5 of 6" compliant.

JIG Level-A Banned Substances	Threshold, Homogeneous Level (1)			
Asbestos	Not intentionally added			
Azo colorants	Not intentionally added			
RoHS - Cadmium/Cadmium Compounds	75 ppm, Not intentionally added (RoHS threshold = 100ppm)			
RoHS - Hexavalent Chromium/Hex.Chromium.Compounds	1000 ppm, Not intentionally added			
RoHS - Lead/Lead Compounds	1000 ppm, Not intentionally added			
RoHS - Mercury/Mercury Compounds	1000 ppm, Not intentionally added			
Ozone Depleting Substances	Class I : Not intentionally added Class II : 1000ppm			
RoHS - Polybrominated Biphenyls (PBBs)	1000 ppm, Not intentionally added			
RoHS - Polybrominated Diphenyl Ethers (PBDEs)	1000 ppm, Not intentionally added			
Polychlorinated Biphenyls (PCBs)	1000 ppm, Not intentionally added			
Polychlorinated Naphthalenes (>3 Chlorine atoms)	1000 ppm, Not intentionally added			
Radioactive Substances	1000 ppm, Not intentionally added			
Shortchain Chlorinated Paraffins	1000 ppm, Not intentionally added			
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	1000 ppm, Not intentionally added			
Tributyl Tin Oxide (TBTO)	1000 ppm, Not intentionally added			
(1) Threshold does not apply to applications covered by a RoHS substance exempt	ion.			

Regarding the EU Directive 2004/12/EC concerning Packaging and Packaging Waste, TI's packing materials (boxes, trays, etc) comply with the directive's requirement that the total concentration of the 4 heavy metals (cadmium, hexavalent chromium, lead, and mercury) must not exceed 100 ppm. Material content details for TI's packing materials are available at www.ti.com/ecoinfo.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at http://www.ti.com/sc/docs/stdterms.htm) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

Signature: (click here for signed certificate)

Name/Title: Cindy Allen, Vice President, Worldwide Quality

Date: September 27, 2006

Pb-Free: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes.

Green: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material).